NOTES

1. MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.

2. FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 250 TO 300 MICROINCHES (6.35 TO 7.62UM) THICK;
GOLD PLATE PER MIL-G-45204, TYPE S, GRADE A, CLASS 1
(40 TO 80 MICROINCHES (1.0 TO 2.0UM) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12 TO 1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076MM MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
AND CORNERS = 0.25MM MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220